Special Issue

Advanced Micro/Nano Manufacturing Technologies for Biomedical Microsystems

Message from the Guest Editor

The focus of this Special Issue will be on advancements in micro/nanomanufacturing technologies for biomedical micro-systems. Topics will include fundamental materials science, traditional manufacturing processes such as photolithography, emerging micro-additive/hybrid technologies such as multimaterial 3D printing, MEMS and NEMS applications, miniaturized robotic systems, and nanomaterials for biosensing. Application areas cover microfluidic/lab-on-a-chip systems for areas such as diagnostics; miniaturized drug delivery systems such as microneedles; materials for neural prosthetics, implants, and scaffolds; and minimally invasive surgical applications and tissue engineering.

Guest Editor

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